

## Edwards STP-iXR1606 Technical Specifications

Inlet flange size	VG200/ VG250	VG150 ISO160F	
	ISO200F/	ICF203	
	ISO250F		
	ICF253/		
	ICF305		
Backing port size	KF40		
Pumping speed N <sub>2</sub>	1600	1000	Litres/second
Pumping speed H2	1200	800	Litres/second
Compression ratio N <sub>2</sub> /H2	>10 <sup>8</sup> / 1x10 <sup>3</sup>		
Ultimate pressure	10 <sup>-7</sup> (10 <sup>-9</sup> )		Pa (Torr)
Allowable backing pressure	266 (2)		Pa (Torr)
Max gas flow $N_2^{*1}$ (water cooled only)	4700 (7.94)		sccm (Pa m <sup>3</sup> /sec)
Max gas flow Ar $^{*1}$ (water cooled only)	1800 (3.04)		sccm (Pa m <sup>3</sup> /sec)
Rated speed	36,500		rpm
Starting time	<8		minutes
Mounting position	Any orientation		
Input voltage	200-240		V
Max input power	750		VA
Weight	48		kg

\*1:The maximum gas flow value applies for N<sub>2</sub> or Ar gas pumped continuously, with water cooling temperature under 25 degree C and a backing pump of 10,000 l/min size or larger used. The value is changed if operated under different conditions



## Edwards STP-iXR1606 **Pumping Curves**

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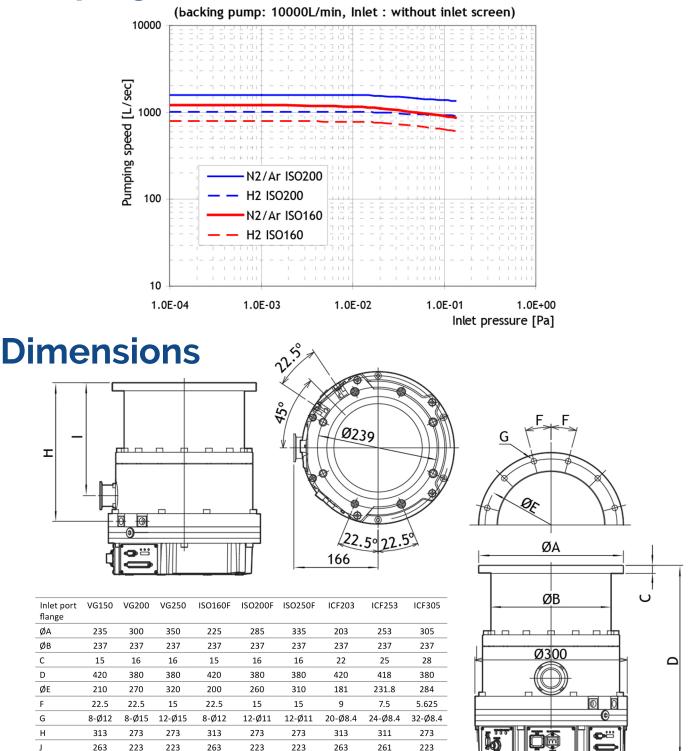
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## Edwards STP-iXR1606 Features & Benefits

- revolutionary, newly developed rotor design
- compact design makes for easy installation & small footprint
- fully integrated onboard controller
- energy saving 32% reduced power consumption in high gas flow area
- highest pumping speed in the 8" TMP class
- corrosion resistant model available

## **Applications**

 plasma etch · ECR etch · film deposition · sputtering · ion implantation source · beam line pumping end station · MBE · diffusion · photo resist stripping · crystal, epitaxial growth · wafer inspection · load lock chambers · surface analysis · mass spectrometry · electron microscopy · high energy physics · radioactive applications

